



US 20220352854A1

(19) **United States**(12) **Patent Application Publication**
OHMAE et al.(10) **Pub. No.: US 2022/0352854 A1**(43) **Pub. Date: Nov. 3, 2022**(54) **POWER AMPLIFYING MODULE**(71) Applicant: **Murata Manufacturing Co., Ltd.**,
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TAKAHASHI, Kyoto (JP)(21) Appl. No.: **17/660,898**(22) Filed: **Apr. 27, 2022**(30) **Foreign Application Priority Data**

Apr. 28, 2021 (JP) 2021-076216

Publication Classification(51) **Int. Cl.**
H03F 1/30 (2006.01)
H03F 3/45 (2006.01)(52) **U.S. Cl.**CPC **H03F 1/30** (2013.01); **H03F 3/45475**
(2013.01); **H03F 2200/09** (2013.01)(57) **ABSTRACT**

In a power amplifying module in which a plurality of differential amplifying circuits is mounted on a substrate, each of the differential amplifying circuits includes a chip device that includes at least two amplifiers, each of the at least two amplifiers amplifying a differential signal, a balun that includes a primary side winding wire and a secondary side winding wire, both ends of the primary side winding wire being connected to an output of the chip device, and a capacitor provided between a power feed point of the primary side winding wire and a reference potential. In at least one of the plurality of the differential amplifying circuits, the distance from one end of the primary side winding wire to the power feed point is different from the distance from the other end of the primary side winding wire to the power feed point.

